

LATM2007 8thIEEELatin-AmericanTestWorkshop



March 11-14, 2007 Cuzco, Peru

LATW2007

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Call for Papers

The IEEE Latin-American Test Workshop provides an annual forum for test and fault tolerance professionals and technologists from Latin America and all over the world to present and discuss various aspects of system, board and component testing and fault-tolerance with design, manufacturing and field considerations in mind. The best papers presented at the 8th LATW will be invited for submission to the IEEE Design and Test of Computers and Journal of Integrated Circuits and Systems.

Topics of interest include but are not limited to:

- Analog Mixed Signal Test
 Automatic Test Generation
 Board and System Test

- Built-In Self-Test
- Defect-Based Test
- Dependability
- Design and Synthesis for Testability
- Design Verification/Validation
- Design for Manufacturability
- Economics of Test

- Fault Analysis and DiagnosisFault Modeling and Simulation
- Fault-Tolerance in HW/SW
- Fault-Tolerant Architectures

- Memory Test and Repair On-Line Testing Process Control and Measurements
- Radiation Hardening Techniques
- System-on-Chip Test Yield Optimization

Topic Coordinators:

Analog and Mixed-Signal - M. Renovell, LIRMM, France DfT & BIST - A. Orailoglu, UC San Diego, USA On-line Test and Fault Tolerance - D. K. Pradhan, University of Bristol, UK Space Radiation - F. Lima, UFRGS, Brazil Verification and High Level Test - M. Reorda, Politecnico di Torino, Italy

Paper Submission Information:

Software Testing - E. Bezerra, PUCRS, Brazil

To encourage and facilitate informal discussion, participation will be limited. Those interested in presenting recent results at the workshop are invited to submit either an extended abstract, one to three pages long, or a full length paper. PDF electronic submissions should be done via the workshop webpage: www.latw.net. Authors should send papers in the IEEE format with a cover letter indicating the complete mail address, phone/fax numbers and e-mail addresses, the contact person and the presenter. Detailed instructions are available at the workshop webpage. The Program Committee also welcomes proposals for panels and special topic sessions. For additional information please contact one of the Program Co-Chairs.

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Raoul Velazco raoul.velazco@imag.fr

Submission deadline: December 3th, 2006 Notification of acceptance: January 14th, 2007 Camera Ready: **January 26th, 2007**

LATW2007 will be held in Cuzco, Peru. The city of Cusco is located at the central and south-eastern zone of Peru. Cusco, was the mythical capital of the Inca Empire. You'll find the amazing artistic legacy from the Incas such as huge temples, palaces and artefacts. Cusco offers beautiful landscapes and an approach to the ancient Inca culture. There you also can find many structures built during the Spanish colony, that evoke the greatness of the Children of the Sun and the Spanish influence after the conquest. Cusco Capital of Andean Culture offers magnificent expressions of Pre-Columbian and Colonial Art. Nowadays Cusco artisans still preserve techniques from this period, mixed with knowledge from the Spanish influence. Colours, friendship, pleasure and a great diversity of customs and traditions, handicrafts and folklore dances.





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